

TC74AC367P, TC74AC367F, TC74AC367FN, TC74AC367FT

HEX BUS BUFFER (3 - STATE)

The TC74AC367 is an advanced high speed CMOS HEX BUS BUFFERs fabricated with silicon gate and double - layer metal wiring C²MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

It contains six buffers ; four buffers are controlled by an enable input ($\overline{G1}$), and the other two buffers are controlled by another enable input ($\overline{G2}$). The outputs of each buffer group are enabled when $\overline{G1}$ and/or $\overline{G2}$ inputs are held low ; if held high, these outputs are in a high impedance state.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

FEATURES :

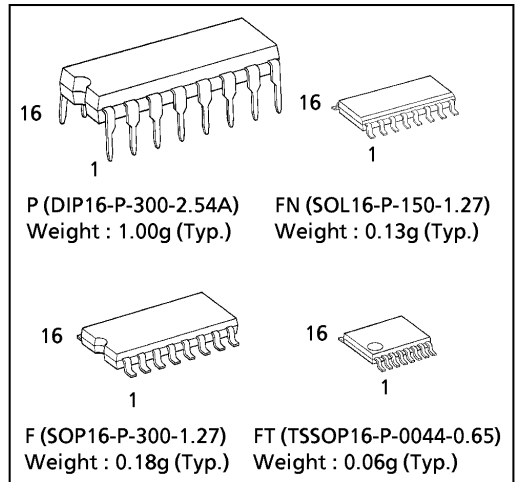
- High Speed..... $t_{pd} = 3.7ns(typ.)$ at $V_{CC} = 5V$
- Low Power Dissipation..... $I_{CC} = 8\mu A(Max.)$ at $T_a = 25^\circ C$
- High Noise Immunity..... $V_{NIH} = V_{NIL} = 28\% V_{CC} (Min.)$
- Symmetrical Output Impedance..... $|I_{OH}| = I_{OL} = 24mA(Min.)$
Capability of driving 50Ω transmission lines.
- Balanced Propagation Delays..... $t_{pLH} \approx t_{pHL}$
- Wide Operating Voltage Range..... $V_{CC} (opr) = 2V \sim 5.5V$
- Pin and Function Compatible with 74F367

TRUTH TABLE

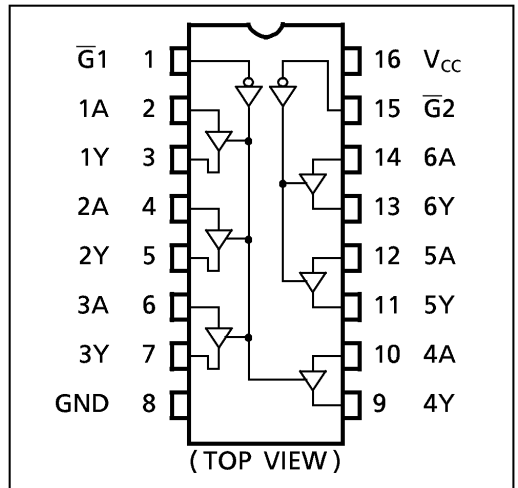
INPUTS		OUTPUTS
\overline{G}	A	Y
L	L	L
L	H	H
H	X	Z

X : Don't Care
Z : High Impedance

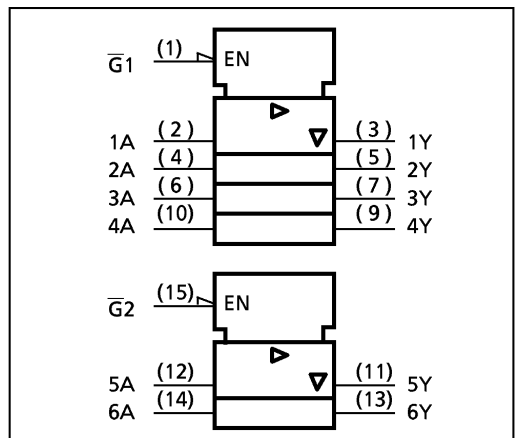
(Note) The JEDEC SOP (FN) is not available in Japan.



PIN ASSIGNMENT



IEC LOGIC SYMBOL



961001EBA2

● TOSHIBA is continually working to improve the quality and the reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property. In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	-0.5~7.0	V
DC Input Voltage	V_{IN}	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 50	mA
DC Output Current	I_{OUT}	± 50	mA
DC V_{CC} /Ground Current	I_{CC}	± 150	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP/TSSOP)	mW
Storage Temperature	T_{stg}	-65~150	°C

*500mW in the range of $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$. From $T_a = 65^{\circ}\text{C}$ to 85°C a derating factor of $-10\text{mW}/^{\circ}\text{C}$ should be applied up to 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	2.0~5.5	V
Input Voltage	V_{IN}	0~ V_{CC}	V
Output Voltage	V_{OUT}	0~ V_{CC}	V
Operating Temperature	T_{opr}	-40~85	°C
Input Rise and Fall Time	dt / dV	0~ 100 ($V_{cc} = 3.3 \pm 0.3\text{V}$) 0~ 20 ($V_{cc} = 5 \pm 0.5\text{V}$)	ns / V

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	$T_a = 25^{\circ}\text{C}$			$T_a = -40 \sim 85^{\circ}\text{C}$		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V_{IH}		2.0	1.50	—	—	1.50	—	V
			3.0	2.10	—	—	2.10	—	
			5.5	3.85	—	—	3.85	—	
Low - Level Input Voltage	V_{IL}		2.0	—	—	0.50	—	0.50	V
			3.0	—	—	0.90	—	0.90	
			5.5	—	—	1.65	—	1.65	
High - Level Output Voltage	V_{OH}	$V_{IN} = V_{IH}$	$I_{OH} = -50\mu\text{A}$	2.0	1.9	2.0	—	1.9	V
				3.0	2.9	3.0	—	2.9	
		$V_{IN} = V_{IL}$	$I_{OH} = -4\text{mA}$ $I_{OH} = -24\text{mA}$ $I_{OH} = -75\text{mA}^*$	4.5	4.4	4.5	—	4.4	
				5.5	—	—	—	—	
Low - Level Output Voltage	V_{OL}	$V_{IN} = V_{IH}$	$I_{OL} = 50\mu\text{A}$	2.0	—	0.0	0.1	—	V
				3.0	—	0.0	0.1	—	
		$V_{IN} = V_{IL}$	$I_{OL} = 12\text{mA}$ $I_{OL} = 24\text{mA}$ $I_{OL} = 75\text{mA}^*$	4.5	—	—	0.36	—	
				5.5	—	—	0.36	—	
3 - State Output Off - State Current	I_{OZ}	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND	5.5	—	—	± 0.5	—	± 5.0	μA
Input Leakage Current	I_{IN}	$V_{IN} = V_{CC}$ or GND	5.5	—	—	± 0.1	—	± 1.0	
Quiescent Supply Current	I_{CC}	$V_{IN} = V_{CC}$ or GND	5.5	—	—	8.0	—	80.0	

* : This spec indicates the capability of driving 50Ω transmission lines.
One output should be tested at a time for a 10ms maximum duration.

961001EBA2'

- The products described in this document are subject to foreign exchange and foreign trade control laws.
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA CORPORATION for any infringements of intellectual property or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any intellectual property or other rights of TOSHIBA CORPORATION or others.
- The information contained herein is subject to change without notice.

AC ELECTRICAL CHARACTERISTICS ($C_L = 50\text{pF}$, $R_L = 500\Omega$, Input $t_r = t_f = 3\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C			Ta = -40~85°C		UNIT
			V _{CC} (V)	MIN.	TYP.	MAX.	MIN.	
Propagation Delay Time	t _{pLH} t _{pHL}		3.3 ± 0.3	—	6.5	11.0	1.0	ns
			5.0 ± 0.5	—	4.5	7.0	1.0	
Output Enable Time	t _{pZL} t _{pZH}		3.3 ± 0.3	—	7.9	13.2	1.0	ns
			5.0 ± 0.5	—	5.5	8.7	1.0	
Output Disable Time	t _{pLZ} t _{pHZ}		3.3 ± 0.3	—	6.3	10.5	1.0	ns
			5.0 ± 0.5	—	5.2	7.9	1.0	
Input Capacitance	C _{IN}		—	5	10	—	10	pF
Output Capacitance	C _{OUT}		—	10	—	—	—	
Power Dissipation Capacitance	C _{PD} (1)		—	28	—	—	—	

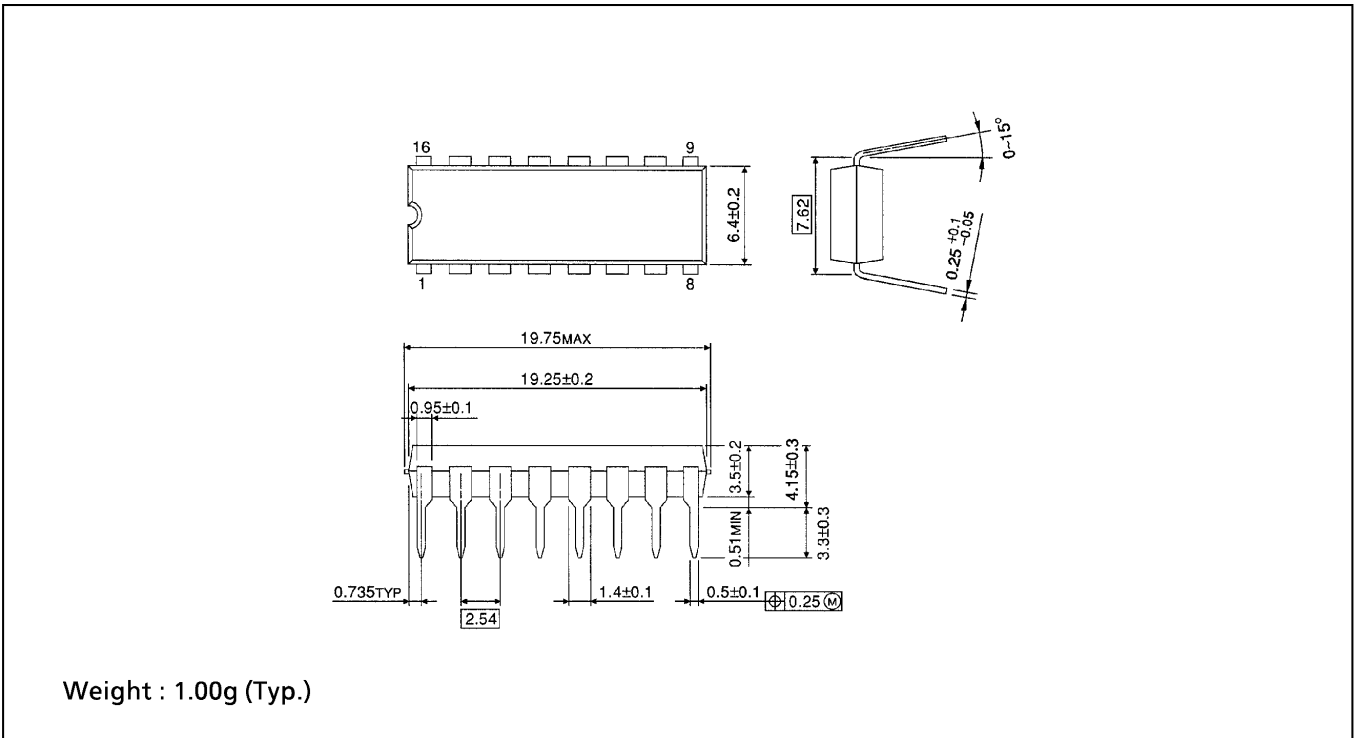
Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC(\text{opr.})} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 6 \text{ (per bit)}$$

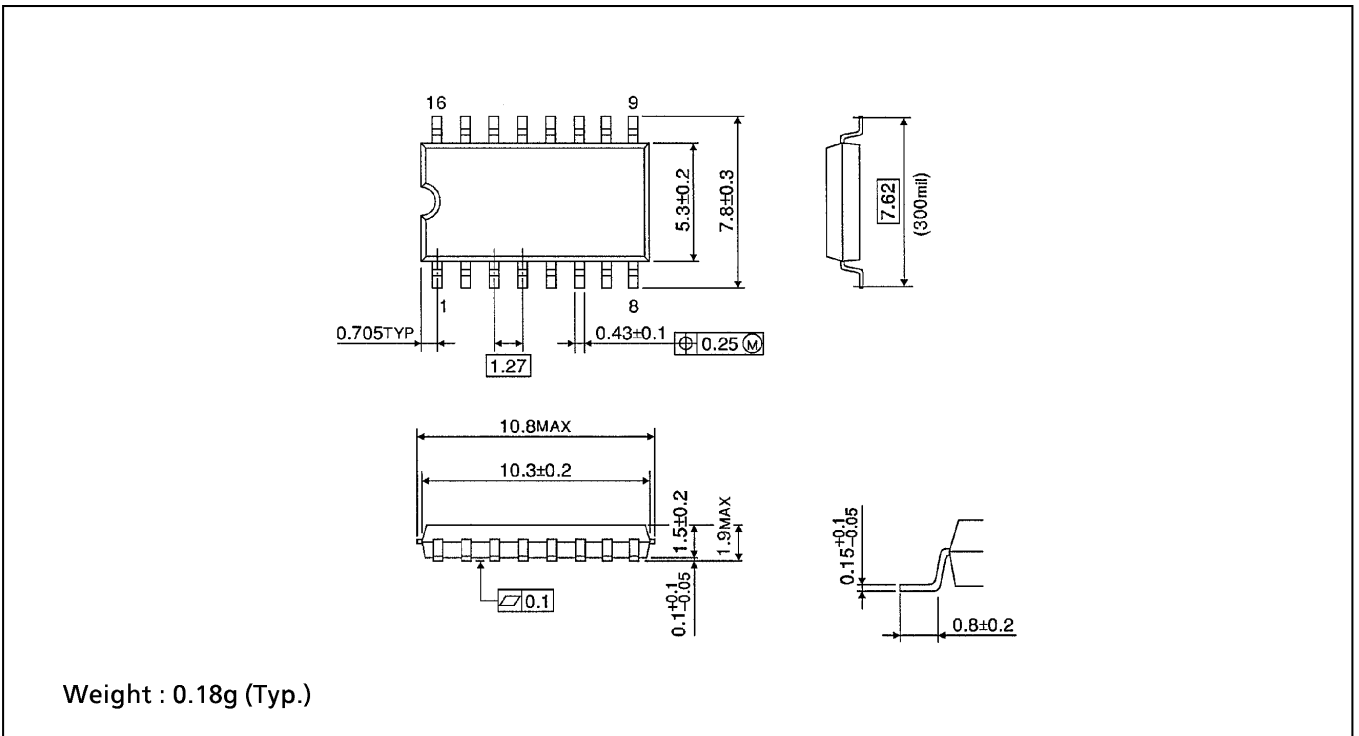
DIP 16PIN OUTLINE DRAWING (DIP16-P-300-2.54A)

Unit in mm



SOP 16PIN (200mil BODY) OUTLINE DRAWING (SOP16-P-300-1.27)

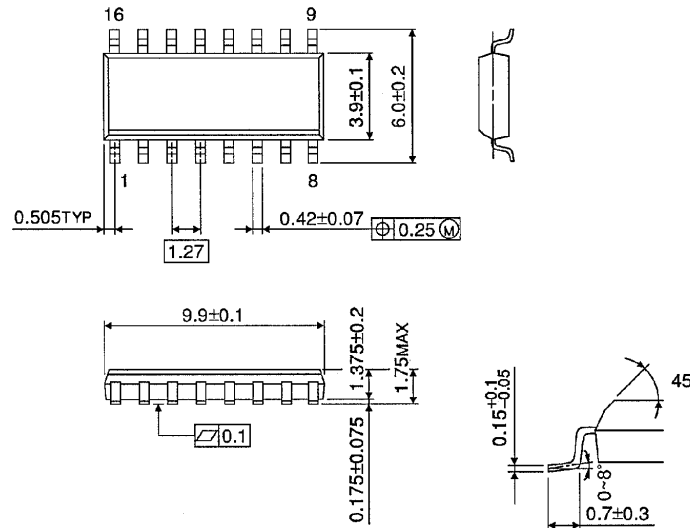
Unit in mm



SOP 16PIN (150mil BODY) OUTLINE DRAWING (SOL16-P-150 -1.27)

Unit in mm

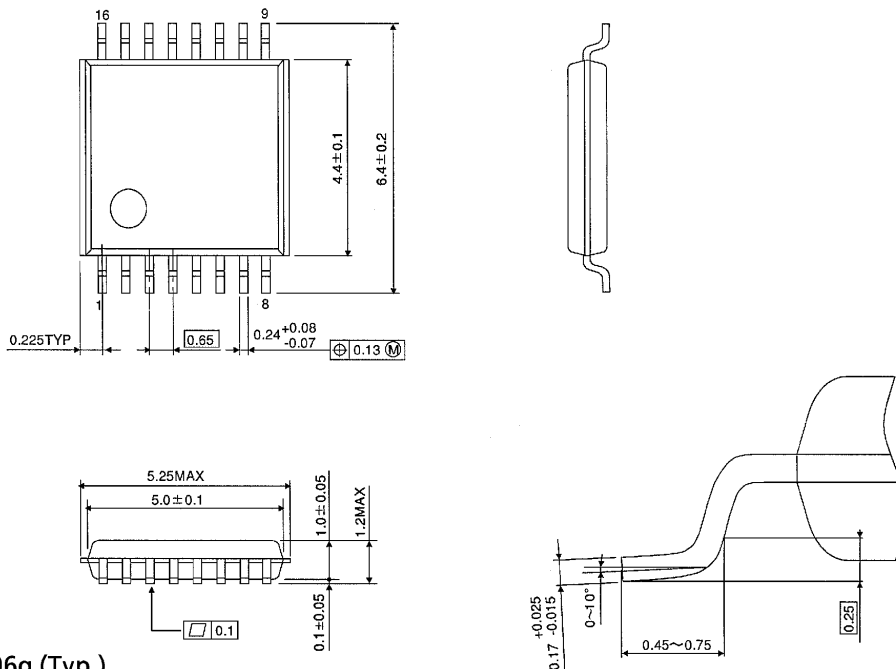
(Note) This package is not available in Japan.



Weight : 0.13g (Typ.)

TSSOP 16PIN OUTLINE DRAWING (TSSOP16-P-0044-0.65)

Unit in mm



Weight : 0.06g (Typ.)